



Product Change Notification

Change Notification #: 117599 - 00
Change Title: Intel® Dual Band Wireless-AC 7265 SKUs:
7265.D2WG.W, 7265.D2WG.S,
7265.D2WG18V, 7265.D2WG18V.S,
7265.D2WG.I, 7265.D2WG.NVB,
PCN 117599-00, Label,
Label Update
Date of Publication: May 22, 2020

Key Characteristics of the Change:
Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	June 15, 2020
---	---------------

Description of Change to the Customer:

Intel® Dual Band Wireless-AC 7265 SKUs listed in the products affected table below will undergo the following change:

1. The China approval ID will be added to product label: CMIIT ID 2019DJ9058 (M)
2. The Intel Tracking revision will be changed on the following product.

Product Code	Before	After
AC7265.D2WG.W	0E	0F

See Labels below.

7265.D2WG.W	Disti Label - Before		
<p>7265.D2WG.W</p> <p>VERSION #: H59008-010</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT</p> <p>CARTON #: VVXXXXXXX</p>	<p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY PACKED BY: XXXXXX</p> <p>BATCH #: CCVVMRDS</p>	<p>QTY: 100</p> <p>1 88334 00140 2</p> <p>9 310779 300005</p>	<p>Intel® Dual Band Wireless-AC 7265 (Model : 7265.D2WG.W)</p> <p>PKG ID (3S) VVVVMMMMDD###PPPPPP100</p> <p>T P/N: GTTTTTTTTT</p> <p>D P/N: P P P P P P REV AXJ HP P/N: 810316-001 REV: 0E</p> <p>Vendor ID Loc Id Mfg Id L P/N: SW16A11619</p> <p>VVVVVLLLLL XXXXXXX EC: 832609</p>
Disti Label - After			
<p>7265.D2WG.W</p> <p>VERSION #: H59008-011</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT</p> <p>CARTON #: VVXXXXXXX</p>	<p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY PACKED BY: XXXXXX</p> <p>BATCH #: CCVVMRDS</p>	<p>QTY: 100</p> <p>1 88334 00140 2</p> <p>9 310779 300005</p>	<p>Intel® Dual Band Wireless-AC 7265 (Model : 7265.D2WG.W)</p> <p>PKG ID (3S) VVVVMMMMDD###PPPPPP100</p> <p>T P/N: GTTTTTTTTT</p> <p>D P/N: P P P P P P REV AXJ HP P/N: 810316-001 REV: 0F</p> <p>Vendor ID Loc Id Mfg Id L P/N: SW16A11619</p> <p>VVVVVLLLLL XXXXXXX EC: 832609</p>

7265.D2WG.S	Disti Label - Before		
<p>7265.D2WG.S</p> <p>VERSION #: H66291-007</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT</p> <p>CARTON #: VVXXXXXXX</p>	<p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY PACKED BY: XXXXXX</p> <p>BATCH #: CCVVMRDS</p>	<p>QTY: 100</p> <p>1 88334 00140 2</p> <p>9 310779 300005</p>	<p>Intel® Dual Band Wireless-AC 7265 (Model : 7265.D2WG.S)</p> <p>PKG ID (3S) VVVVMMMMDD###PPPPPP100</p> <p>T P/N: GTTTTTTTTT</p> <p>D P/N: P P P P P P REV AXJ HP P/N: XXXXXX-XXX REV: XX</p> <p>Vendor ID Loc Id Mfg Id L P/N: XXXXXXXXXX</p> <p>VVVVVLLLLL XXXXXXX EC: XXXXXX</p>
Disti Label - After			
<p>7265.D2WG.S</p> <p>VERSION #: H66291-008</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT</p> <p>CARTON #: VVXXXXXXX</p>	<p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY PACKED BY: XXXXXX</p> <p>BATCH #: CCVVMRDS</p>	<p>QTY: 100</p> <p>1 88334 00140 2</p> <p>9 310779 300005</p>	<p>Intel® Dual Band Wireless-AC 7265 (Model : 7265.D2WG.S)</p> <p>PKG ID (3S) VVVVMMMMDD###PPPPPP100</p> <p>T P/N: GTTTTTTTTT</p> <p>D P/N: P P P P P P REV AXJ HP P/N: XXXXXX-XXX REV: XX</p> <p>Vendor ID Loc Id Mfg Id L P/N: XXXXXXXXXX</p> <p>VVVVVLLLLL XXXXXXX EC: XXXXXX</p>

7265.D2WG18V	Disti Label - Before			
	7265.D2WG18V VERSION #: H60230-008 MM#: XXXXXX QTY: 100 PACK DATE: DD MMM YY PACKED BY: XXXXXX BATCH #: CCVYMDRSS MADE IN CHINA WITH PARTIAL FOREIGN CONTENT CARTON #: VVXXXXXXXXXX 	Intel® Dual Band Wireless-AC 7265 (Model : 7265D2W) PKG ID (3S) VVVVMMMMDDDD###PPPPPP100 T P/N: GTTTTTTTTT D P/N: P P P P P P REV AX X HP P/N: XXXXXX-XXX REV: XX PACKAGE WEIGHT: 6.1 LBS Vendor ID Loc Id Mfg Id L P/N: SW10M73248 VVVVVLLLLL MNNMM EC: 1854498	<p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1940 USA www.intel.com</p> <p>MSP: CRM-INT-7265D2W</p>	
7265.D2WG18V.S	Disti Label - After			
	7265.D2WG18V VERSION #: H60230-009 MM#: XXXXXX QTY: 100 PACK DATE: DD MMM YY PACKED BY: XXXXXX BATCH #: CCVYMDRSS MADE IN CHINA WITH PARTIAL FOREIGN CONTENT CARTON #: VVXXXXXXXXXX 	Intel® Dual Band Wireless-AC 7265 (Model : 7265D2W) PKG ID (3S) VVVVMMMMDDDD###PPPPPP100 T P/N: GTTTTTTTTT D P/N: P P P P P P REV AX X HP P/N: XXXXXX-XXX REV: XX PACKAGE WEIGHT: 6.1 LBS Vendor ID Loc Id Mfg Id L P/N: SW10M73248 VVVVVLLLLL MNNMM EC: 1854498	<p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1940 USA www.intel.com</p> <p>MSP: CRM-INT-7265D2W</p> <p>CMIT ID: 2019010058 (M)</p>	

7265.D2WG18V.S	Disti Label - Before			
	7265.D2WG18V.S VERSION #: H60233-007 MM#: XXXXXX QTY: 100 PACK DATE: DD MMM YY PACKED BY: XXXXXX BATCH #: CCVYMDRSS MADE IN CHINA WITH PARTIAL FOREIGN CONTENT CARTON #: VVXXXXXXXXXX 	Intel® Dual Band Wireless-AC 7265 (Model : 7265D2W) PKG ID (3S) VVVVMMMMDDDD###PPPPPP100 T P/N: G0M48090206 D P/N: P P P P P P REV AX X HP P/N: XXXXXX-XXX REV: XX PACKAGE WEIGHT: 6.1 LBS Vendor ID Loc Id Mfg Id L P/N: XXXXXX000X VVVVVLLLLL MNNMM EC: XXXXXX	<p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1940 USA www.intel.com</p> <p>MSP: CRM-INT-7265D2W</p>	
7265.D2WG18V.S	Disti Label - After			
	7265.D2WG18V.S VERSION #: H60233-008 MM#: XXXXXX QTY: 100 PACK DATE: DD MMM YY PACKED BY: XXXXXX BATCH #: CCVYMDRSS MADE IN CHINA WITH PARTIAL FOREIGN CONTENT CARTON #: VVXXXXXXXXXX 	Intel® Dual Band Wireless-AC 7265 (Model : 7265D2W) PKG ID (3S) VVVVMMMMDDDD###PPPPPP100 T P/N: G0M48090206 D P/N: P P P P P P REV AX X HP P/N: XXXXXX-XXX REV: XX PACKAGE WEIGHT: 6.1 LBS Vendor ID Loc Id Mfg Id L P/N: XXXXXX000X VVVVVLLLLL MNNMM EC: XXXXXX	<p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1940 USA www.intel.com</p> <p>MSP: CRM-INT-7265D2W</p> <p>CMIT ID: 2019010058 (M)</p>	

7265.D2WG.I		Disti Label - Before	
<p>7265.D2WG.I</p> <p>VERSION #: H92392-006</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT</p> <p>CARTON #: VVXXXXXXXX</p>		<p>QTY: 100</p> <p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY</p> <p>PACKED BY: XXXXXX</p> <p>BATCH #: CCVVMRDS</p>	
<p>Intel® Dual Band Wireless-AC 7265 (Model: 7265D2W)</p> <p>PKG ID (3S) VVVVMMMMDDDD###PPPPPP100</p> <p>D P/N: P P P P P P REV AXJX HP P/N: XXXXXX-XXX REV: XX</p> <p>Vendor ID Loc Id Mfg Id L P/N: XXXXXXXXXX</p> <p>VVVVVLLLLL XXXXXXX EC: XXXXXXXX</p>		<p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1649 USA www.intel.com</p> <p>MSIP-CRM-INT-7265D2W</p>	
7265.D2WG.I		Disti Label - After	
<p>7265.D2WG.I</p> <p>VERSION #: H92392-007</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT</p> <p>CARTON #: VVXXXXXXXX</p>		<p>QTY: 100</p> <p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY</p> <p>PACKED BY: XXXXXX</p> <p>BATCH #: CCVVMRDS</p>	
<p>Intel® Dual Band Wireless-AC 7265 (Model: 7265D2W)</p> <p>PKG ID (3S) VVVVMMMMDDDD###PPPPPP100</p> <p>D P/N: P P P P P P REV AXJX HP P/N: XXXXXX-XXX REV: XX</p> <p>Vendor ID Loc Id Mfg Id L P/N: XXXXXXXXXX</p> <p>VVVVVLLLLL XXXXXXX EC: XXXXXXXX</p>		<p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1649 USA www.intel.com</p> <p>MSIP-CRM-INT-7265D2W</p>	

7265.D2WG.NVB		Disti Label - Before	
<p>7265.D2WG.NVB</p> <p>VERSION #: H85435-009</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT</p> <p>CARTON #: VVXXXXXXXX</p>		<p>QTY: 100</p> <p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY</p> <p>PACKED BY: XXXXXX</p> <p>BATCH #: CCVVMRDS</p>	
<p>Intel® Dual Band Wireless-AC 7265 (Model: 7265D2W)</p> <p>PKG ID (3S) VVVVMMMMDDDD###PPPPPP100</p> <p>D P/N: P P P P P P REV AXJX HP P/N: XXXXXX-XXX REV: XX</p> <p>Vendor ID Loc Id Mfg Id L P/N: XXXXXXXXXX</p> <p>VVVVVLLLLL XXXXXXX EC: XXXXXXXX</p>		<p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1649 USA www.intel.com</p> <p>MSIP-CRM-INT-7265D2W</p>	
7265.D2WG.NVB		Disti Label - After	
<p>7265.D2WG.NVB</p> <p>VERSION #: H85435-010</p> <p>MADE IN CHINA WITH PARTIAL FOREIGN CONTENT</p> <p>CARTON #: VVXXXXXXXX</p>		<p>QTY: 100</p> <p>MM#: XXXXXX</p> <p>PACK DATE: DD MMM YY</p> <p>PACKED BY: XXXXXX</p> <p>BATCH #: CCVVMRDS</p>	
<p>Intel® Dual Band Wireless-AC 7265 (Model: 7265D2W)</p> <p>PKG ID (3S) VVVVMMMMDDDD###PPPPPP100</p> <p>D P/N: P P P P P P REV AXJX HP P/N: XXXXXX-XXX REV: XX</p> <p>Vendor ID Loc Id Mfg Id L P/N: XXXXXXXXXX</p> <p>VVVVVLLLLL XXXXXXX EC: XXXXXXXX</p>		<p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1649 USA www.intel.com</p> <p>MSIP-CRM-INT-7265D2W</p>	

Customer Impact of Change and Recommended Action:

The label changes to the products do not affect functionality. Intel anticipates no impact to customers.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
7265.D2WG.W	939403	H59008-010	H59008-011
7265.D2WG.S	934470	H66291-007	H66291-008
7265.D2WG18V	934449	H60230-008	H60230-009
7265.D2WG18V.S	934460	H60233-007	H60233-008
7265.D2WG.I	936899	H92392-006	H92392-007
7265.D2WG.NVB	944431	H85435-009	H85435-010

PCN Revision History:

Date of Revision:

May 22, 2020

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

117599 - 00

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

A "Mission Critical Application" is any application in which failure of the Intel Product could result, directly or indirectly, in personal injury or death. SHOULD YOU PURCHASE OR USE INTEL'S PRODUCTS FOR ANY SUCH MISSION CRITICAL APPLICATION, YOU SHALL INDEMNIFY AND HOLD INTEL AND ITS SUBSIDIARIES, SUBCONTRACTORS AND AFFILIATES, AND THE DIRECTORS, OFFICERS, AND EMPLOYEES OF EACH, HARMLESS AGAINST ALL CLAIMS COSTS, DAMAGES, AND EXPENSES AND REASONABLE ATTORNEYS' FEES ARISING OUT OF, DIRECTLY OR INDIRECTLY, ANY CLAIM OF PRODUCT LIABILITY, PERSONAL INJURY, OR DEATH ARISING IN ANY WAY OUT OF SUCH MISSION CRITICAL APPLICATION, WHETHER OR NOT INTEL OR ITS SUBCONTRACTOR WAS NEGLIGENT IN THE DESIGN, MANUFACTURE, OR WARNING OF THE INTEL PRODUCT OR ANY OF ITS PARTS.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined". Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2020. Other names and brands may be claimed as the property of others.

3D XPoint, ACEX, Altera, APEX, AnyWAN, Arria, Avalon, Axxia, BlueMoon, BunnyPeople, Celeron, Centrino, Cilk, CONVERGATE, Cyclone, Docea, eASIC, easicopy, Empirion, Flexpipe, Hyperflex, Intel, the Intel logo, Intel Adaptix, Intel Agilix, Intel Atom, Intel CoFluent, Intel Core, Intel. Experience What's Inside, the Intel. Experience What's Inside logo, Intel Falcon, Intel Inside, the Intel Inside logo, Intel Nervana, Intel Optane, Intel RealSense, Intel Shooting Star, Intel Sirius, Intel SpeedStep, Intel Unite, Intel vPro, Intel Xeon Phi, Iris, Itanium, MAX, Movidius, Myriad, neon, Nios, OpenVINO, the OpenVINO logo, Pentium, Puma, Quark, Quartus, SICOFI, Simics, SMARTi, SoftSilicon, Sound Mark, StarPro, Stratix, the Stratix logo, Stay With It, the Engineering Stay With It logo, StreamSight, Tarari, The Journey Inside, Thunderbolt, the Thunderbolt logo, Transcede, Ultrabook, VTune, Xeon, X-GOLD, XMM, X-PMU and XPOSYS are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.

Microsoft, Windows, and the Windows logo are trademarks, or registered trademarks of Microsoft Corporation in the United States and/or other countries. Java is a registered trademark of Oracle and/or its affiliates. Bluetooth is a trademark owned by its proprietor and used by Intel Corporation under license. Intel Corporation uses the Palm OS® Ready mark under license from Palm, Inc. OpenCL and the OpenCL logo are trademarks of Apple Inc. used by permission by Khronos. Learn how to use Intel Trademarks and Brands correctly at <http://www.intel.com/intel/legal/tmusage2.htm>.